

1. Features

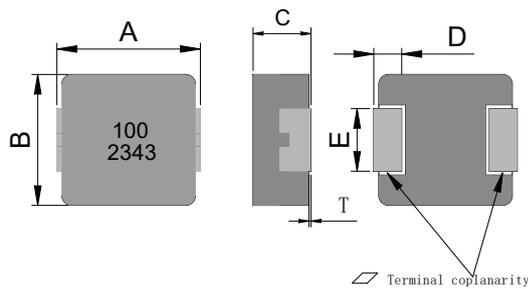
1. Low loss realized with low DCR.
2. High performance realized by metal dust core.
3. Ultra low buzz noise, due to composite construction.
4. 100% Lead(Pb)-Free and RoHS compliant.
5. High reliability -Reliability test complied to AEC-Q200.



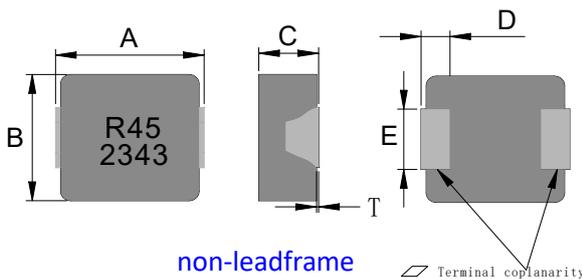
2. Applications

Automotive applications.

3. Dimensions

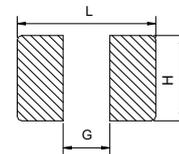


leadframe



non-leadframe

Recommend PC Board Pattern



L(mm)	G(mm)	H(mm)
13.6	5.4	3.5

Note: 1.PCB layout is referred to standard IPC-7351B
 2. The above PCB layout reference only.
 3. Recommend solder paste thickness at 0.15mm and above.

Series	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)	∟(mm)	T(mm)
TMPC1004HV	11.0±0.5	10.0±0.3	3.8±0.2	2.3±0.3	3.0±0.3	≤0.10	0~0.25

4. Part Numbering



A: Series
 B: Dimension
 C: Type
 D: Inductance
 E: Inductance Tolerance
 F: DateCode
 G:Code

BxC
 Carbonyl Powder,vehicle.
 100=10.0uH
 M=±20%
 Marking: Black.100 and 2119(21YY,19 WW, follow production date).

5. Specification

Part Number	Inductance L0 (uH)±20%	I rms (A)		I sat (A)		DCR (mΩ) Typ	DCR (mΩ) Max	Type
		Typ	Max	Typ	Max			
TMPC1004HV-R15YG-D-HD	0.15±30%	43	40	75	70	0.5	0.6	non-leadframe
TMPC1004HV-R22MG-D-HD	0.22	35	33	60	57	0.8	1.0	non-leadframe
TMPC1004HV-R33MG-D-HD	0.33	31	29	60	50	1.0	1.2	non-leadframe
TMPC1004HV-R36MG-D-HD	0.36	31	28	60	48	1.05	1.2	non-leadframe
TMPC1004HV-R47MG-D-HD	0.47	28	25	43	40	1.3	1.5	non-leadframe
TMPC1004HV-R56MG-D-HD	0.56	25	24	40	38	1.6	1.8	non-leadframe
TMPC1004HV-R68MG-D-HD	0.68	22	21	39	37	2.4	2.7	non-leadframe
TMPC1004HV-1R0MG-D-HD	1.00	18	17	36	34	3.0	3.3	non-leadframe
TMPC1004HV-1R5MG-D-HD	1.50	16	15	33	31	4.0	4.6	non-leadframe
TMPC1004HV-2R2MG-D-HD	2.20	12	11	27	25	6.5	7.0	leadframe
TMPC1004HV-3R3MG-D-HD	3.30	11	10	20	18	10.8	11.8	leadframe
TMPC1004HV-4R7MG-D-HD	4.70	10	9.0	17	16	15.0	15.5	leadframe
TMPC1004HV-5R6MG-D-HD	5.60	9.0	8.5	14	13	17	19.3	leadframe
TMPC1004HV-6R8MG-D-HD	6.80	8.5	7.5	13.5	12.3	17.5	23.3	leadframe
TMPC1004HV-8R2MG-D-HD	8.20	8.0	6.8	12.5	11.5	20	22.5	leadframe
TMPC1004HV-100MG-D-HD	10.0	7.5	6.3	12.0	11	27.0	30	leadframe
TMPC1004HV-150MG-D-HD	15.0	6.25	5.7	10	9.5	40	45	leadframe
TMPC1004HV-220MG-D-HD	22.0	5.0	4.5	7.0	6.5	64	74	leadframe
TMPC1004HV-330MG-D-HD	33.0	3.5	3.0	5.0	4.5	92	112	leadframe
TMPC1004HV-470MG-D-HD	47.0	3.0	2.5	4.5	4.0	145	167	leadframe
TMPC1004HV-680MG-D-HD	68.0	2.0	1.8	3.0	2.5	205	240	leadframe
TMPC1004HV-820MG-D-HD	82.0	1.5	1.2	2.5	2.0	265	320	leadframe
TMPC1004HV-101MG-D-HD	100.0	1.3	1.1	2.4	1.9	362	420	leadframe

Note:

1. Test frequency : Ls : 100KHz /1.0V.
2. All test data referenced to 25°C ambient.
3. Testing Instrument(or equ) : Agilent 4284A,E4991A,4339B,KEYSIGHT E4980A/AL,chroma3302,3250,16502.
4. Heat Rated Current (Irms) will cause the coil temperature rise approximately ΔT of 40°C
5. Saturation Current (Isat) will cause L0 to drop approximately 30%.
6. The part temperature (ambient + temp rise) should not exceed 125°C under worst case operating conditions.Circuit design,component,PCB trace size and thickness,airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
7. Special inquiries besides the above common used types can be met on your requirement.
8. Irms Testing : Temperature rise is highly dependent on many factors including pcb land pattern, trace size, and proximity to other components.
Therefore temperature rise should be verified in application conditions.
9. Rated DC current: The lower value of Irms and Isat.

6. Typical Performance Curves

